

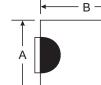
1.5A SURFACE MOUNT GLASS PASSIVATED RECTIFIER

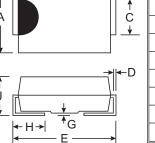
Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 50A Peak
- Ideally Suited for Automated Assembly
- Lead Free Finish/RoHS Compliant (Note 3)

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number, See Page 2
- Ordering Information: See Page 2
- Approximate Weight: SMA 0.064 grams
 SMB 0.093 grams





Dim	SI	ΛA	SMB			
	Min	Max	Min	Мах		
Α	2.29	2.92	3.30	3.94		
В	4.00	4.60	4.06	4.57		
С	1.27	1.63	1.96	2.21		
D	0.15	0.31	0.15	0.31		
Е	4.80	5.59	5.00	5.59		
G	0.10	0.20	0.10	0.20		
н	0.76	1.52	0.76	1.52		
J	2.01	2.62	2.00	2.62		
All Dimensions in mm						

A Suffix Designates SMA Package No Suffix Designates SMB Package

 $@T_A = 25^{\circ}C$ unless otherwise specified

Maximum Ratings and Electrical Characteristics

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic		Symbol	S2 A/AA	S2 B/BA	S2 D/DA	S2 G/GA	S2 J/JA	S2 K/KA	S2 M/MA	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage		V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @	T _T = 100°C	I _(AV)				1.5		•		А
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load		I _{FSM}	50					А		
Forward Voltage	@ I _F = 1.5A	VFM				1.15				V
	$\begin{array}{rl} T_A = & 25^\circ C \\ T_A = & 125^\circ C \end{array}$	I _{RM}				5.0 125				μA
Typical Total Capacitance (Note 1)		CT	20					pF		
Typical Thermal Resistance, Junction to Terminal (Note 2)		$R_{\theta JT}$	20					°C/W		
Operating and Storage Temperature Range		Tj, TSTG	-65 to +150					°C		

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

2. Thermal Resistance Junction to Terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.

3. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.



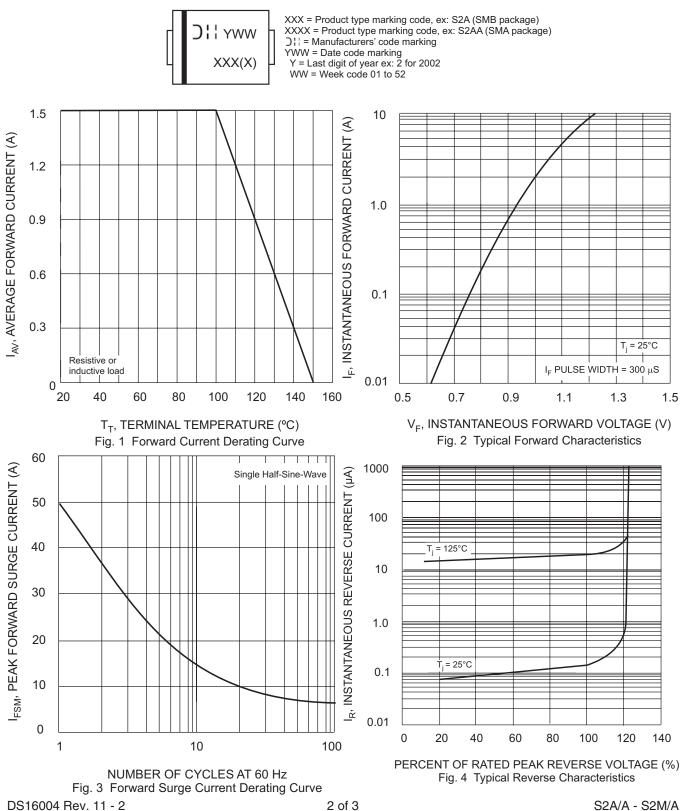
Ordering Information (Note 4)

Device*	Packaging	Shipping
S2xA-13-F	SMA	5000/Tape & Reel
S2x-13-F	SMB	3000/Tape & Reel

* x = Device type, e.g. S2AA-13-F (SMA package); S2A-13-F (SMB package).

Notes: 4. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



www.diodes.com



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